

WHAT IS CLAIMED IS:

1. A crystal oscillation device comprising:  
a crystal oscillator with a package having first connecting electrodes on a flat bottom surface; and  
a flat thin circuit board having circuit components and second connecting electrodes corresponding to the first connecting electrodes on one principal surface; wherein  
the first connecting electrodes are electrically connected to the second connecting electrodes with solder therebetween;  
at least one of the solder and a top surface of at least one of the circuit components define supports for the crystal oscillator; and  
the highest of the supports is one of the circuit components.
2. A crystal oscillation device according to Claim 1, wherein all of the supports for the crystal oscillator are defined by the circuit components.
3. A crystal oscillation device according to Claim 1, wherein all of the supports are substantially equal in height.
4. A crystal oscillation device according to Claim 1, wherein a spacer is attached to at least one of the supports other than a highest of the supports.

5. A crystal oscillation device according to Claim 1, wherein the circuit components include a molded resin component.

6. A crystal oscillation device according to Claim 1, wherein the supports are positioned to support the crystal oscillator on the circuit board even in a state in which the solder for connecting the first connecting electrodes and the second connecting electrodes is not provided.

7. A crystal oscillation device according to Claim 1, wherein the first connecting terminals and the second connecting terminals are disposed inside an outermost edge of the crystal oscillator and the circuit board.

8. An electronic device comprising a crystal oscillation device according to Claim 1.

9. A crystal oscillation device according to Claim 2, wherein all of the supports are substantially equal in height.

10. A crystal oscillation device according to Claim 2, wherein the circuit component defining one of the supports is a molded resin component.

11. A crystal oscillation device according to Claim 3, wherein the circuit component defining one of the supports is a molded resin component.

12. A crystal oscillation device according to Claim 4, wherein the circuit component defining one of the supports is a molded resin component.

13. A crystal oscillation device according to Claim 1, wherein the solder is hour-glass shaped.

14. A crystal oscillation device according to Claim 2, wherein the supports are positioned to support the crystal oscillator on the circuit board even in a state in which the solder for connecting the first connecting electrodes and the second connecting electrodes is not provided.

15. A crystal oscillation device according to Claim 3, wherein the supports are positioned to support the crystal oscillator on the circuit board even in a state in which the solder for connecting the first connecting electrodes and the second connecting electrodes is not provided.

16. A crystal oscillation device according to Claim 4, wherein the supports are positioned to support the crystal oscillator on the circuit board even in a state in which the

solder for connecting the first connecting electrodes and the second connecting electrodes is not provided.

17. A crystal oscillation device according to Claim 1, wherein the circuit components include at least one of a transistor and a varicap diode.

18. A crystal oscillation device according to Claim 2, wherein the first connecting terminals and the second connecting terminals are disposed inside an outermost edge of the crystal oscillator and the circuit board.

19. A crystal oscillation device according to Claim 1, wherein an outer edge of the crystal oscillator is within an outer edge of the circuit board in a plan view.

20. A crystal oscillation device according to Claim 1, wherein the solder does not protrude outward from the outer edges of the crystal oscillator and the outer edges of the thin flat circuit board.